

Claims

1. A releasing layer transfer film for forming a releasing layer onto an insulating layer serving as a component of a COF flexible printed wiring board, characterized in that the releasing layer transfer film comprises a transfer film substrate, and a transferable releasing layer provided on a surface of the transfer film substrate, wherein the transferable releasing layer is formed from a releasing agent and can be transferred onto the insulating layer.

2. A releasing layer transfer film according to claim 1, wherein the transferable releasing layer comprises a silicone-based compound.

3. A releasing layer transfer film according to claim 2, wherein the transferable releasing layer is formed from a releasing agent containing at least one species selected from among a siloxane compound, a silane compound, and silica sol.

4. A releasing layer transfer film according to claim 2, wherein the transferable releasing layer is formed from a releasing agent containing at least one species selected from a silane compound and silica sol.

5. A releasing layer transfer film according to claim 4, wherein the transferable releasing layer is formed from a releasing agent containing a silazane compound.

6. A releasing layer transfer film according to claim 3, wherein the transferable releasing layer is formed by

applying a solution of the releasing agent onto the transfer film substrate, and heating.

7. A releasing layer transfer film according to claim 4, wherein the transferable releasing layer is formed by applying a solution of the releasing agent onto the transfer film substrate, and heating.

8. A releasing layer transfer film according to claim 5, wherein the transferable releasing layer is formed by applying a solution of the releasing agent onto the transfer film substrate, and heating.

9. A releasing layer transfer film according to any of claims 1 to 8, wherein the transferable releasing layer is transferred by firmly affixing the transferable releasing layer to the insulating layer, followed by heating.

10. A releasing layer transfer film according to any of claims 1 to 8, wherein the transferable releasing layer is provided on a surface of the transfer film substrate continuously or in the form of dispersed islands.

11. A releasing layer transfer film according to any of claims 1 to 8, wherein the transferable releasing layer is transferred onto the insulating layer continuously or in the form of dispersed islands.

12. A releasing layer transfer film according to any of claims 1 to 8, wherein the transferable releasing layer is provided so as to correspond to a region for forming the wiring pattern, the region intervening in at least two rows of sprocket holes of the COF flexible printed wiring board.

13. A releasing layer transfer film according to claim 12, wherein the COF flexible wiring board has at least two rows of wiring-pattern-formed regions, and the transferable releasing layer is provided such that a plurality of stripes of the layer correspond to the wiring patterns.

14. A releasing layer transfer film according to any of claims 1 to 8, which has, between the transfer film substrate and the transferable releasing layer, an adhesion layer that can be exclusively released from the transferable releasing layer.

15. A releasing layer transfer film according to any of claims 1 to 8, wherein the transfer film substrate is affixed onto the insulating layer so as to serve as a reinforcing film during a production step of the COF flexible printed wiring board.

16. A releasing layer transfer film according to any of claims 1 to 8, which has, on a surface of the transferable releasing layer, a peelable film that can be peeled from the transferable releasing layer.

17. A laminate film, characterized in that the laminate film comprises a film substrate, a releasing layer provided on a surface of the film substrate, and an insulating layer provided on the surface of the releasing layer opposite the side of the film substrate, wherein the releasing layer is formed from a releasing agent containing at least one species selected from a silane compound and silica sol, and the insulating layer serves as a member of a COF flexible printed

wiring board.

18. A laminate film according to claim 17, wherein the releasing layer is formed from a releasing agent containing a silazane compound.

19. A laminate film according to claim 17, which has a conductor layer on the surface of the insulating layer opposite the side of the releasing layer.

20. A laminate film according to claim 17, which has, between the film substrate and the releasing layer, an adhesion layer that can be exclusively released from the releasing layer.

21. A laminate film according to any of claims 17 to 20, wherein the film substrate is affixed onto the insulating layer so as to serve as a reinforcing film during a production step of the COF flexible printed wiring board.

22. A laminate film according to any of claims 17 to 20, wherein the film substrate is peeled prior to mounting of a semiconductor chip on the COF flexible printed wiring board, thereby leaving the releasing layer on the insulating layer.

23. A laminate film according to claim 22, wherein the releasing layer is transferred onto the insulating layer through heating during the course of peeling of the film substrate.

24. A laminate film according to claim 23, wherein the releasing layer is transferred onto a surface of the insulating layer continuously or in the form of dispersed

islands.